## **LNJ311G83RA**

### Hight Bright Surface Mounting Chip LED

3216 Type

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol Rating		Unit		
Power dissipation	$P_{\mathrm{D}}$	55	mW		
Forward current	$I_{\mathrm{F}}$	20	mA		
Pulse forward current *	$I_{FP}$	60	mA		
Reverse voltage	$V_R$	4	V		
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C		
Storage temperature	T <sub>stg</sub>	-40 to +100	°C		

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

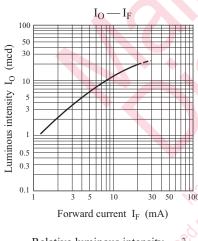
#### ■ Lighting Color

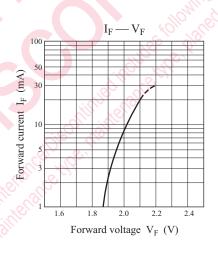
• Yellow Green

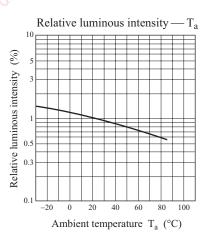
#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

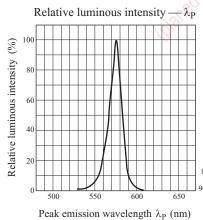
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Parameter	Symbol	Conditions	Min	Typ	/lax	Unit
Luminous intensity *	I <sub>O</sub>	$I_F = 10 \text{ mA}$	6.4	12.0	2,	mcd
Reverse current	$I_R$	$V_R = 4 V$	111		100	μΑ
Forward voltage	$V_{\rm F}$	$I_F = 10 \text{ mA}$	9110	2.03	2.5	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$	in the	575		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$	OLILI	15		nm

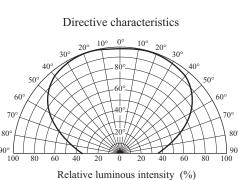
Note) \*: Measurement tolerance: ±20%

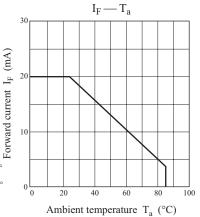








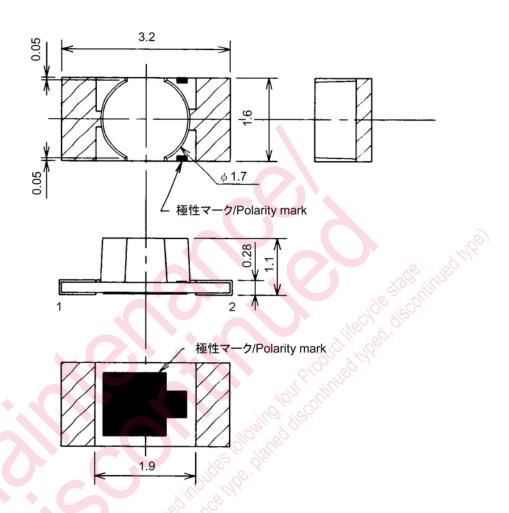




LNJ311G83RA Panasonic

■ Package (Unit: mm)

## KLTFTN2K1100



- Pin name
  - 1: Anode
  - 2: Cathode

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